

10/009822

FILED UNDER 35 U.S.C. 371

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10009822	FILING DATE 12/13/2001	CLASS 361	SUBCLASS	GAU 2835	EXAMINER KOENIGER LA VILLA
----------------------	---------------------------	--------------	----------	-------------	--

****APPLICANTS:** Osada Mitsuo; Hirayama Norio; Arikawa Tadashi; Amano Yoshinoro; Maesato Hidetoshi; Hayashi Hidefumi; Murai Hiroshi; 12/20/2001 = +

****CONTINUING DATA VERIFIED:**
THIS APPLICATION IS A 371 OF PCT/JP01/03164 04/12/2001 *ok m*

**** FOREIGN APPLICATIONS VERIFIED:**
JAPAN 17584/2000 01/26/2000
JAPAN 113006/2000 04/14/2000 *two ok*
JAPAN 372405/2000 12/07/2000 *m*

PG-PUB ☐ DO NOT PUBLISH ☐ RESCIND ☐

Foreign priority claimed ☒ yes ☐ no
35 USC 119 conditions met ☒ yes ☐ no
Verified and Acknowledged Examiners's initials *m*

ATTORNEY DOCKET NO
Q67726

TITLE : Material of heat-dissipating plate on which semiconductor is mounted, method for fabricating the same, and ceramic package produced by using the same

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

BEST AVAILABLE COPY

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED		
		Total Claims 6		Print Claim for O.G. 1
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drawn 3	Figs. Drawn 7	Print Figs. 4
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner		
		PREPARED FOR ISSUE		
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.				

FILED WITH:

☐ DISK (CRF)☐ CD-ROM

(Attached in pocket on right inside flap)